

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

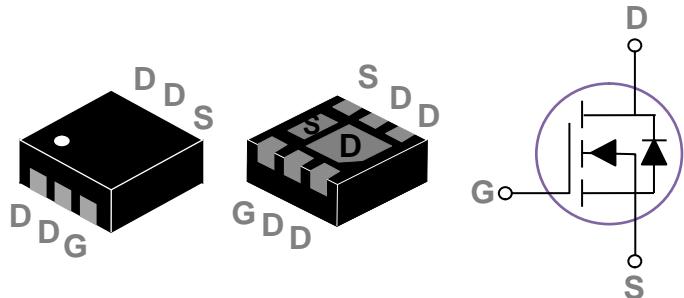
- 30V, 7.8A, RDS(ON) = $20m\Omega$  @VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available
- Marking : VA

### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

BVDSS	RDS(ON)	ID
30V	$20m\Omega$	7.8A

### DFN2x2-6L 2EP Pin Configuration



### Absolute Maximum Ratings T<sub>c</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>A</sub> =25°C)	7.8	A
	Drain Current – Continuous (T <sub>A</sub> =70°C)	6.2	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	31.2	A
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> =25°C)	2.01	W
	Power Dissipation – Derate above 25°C	0.016	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.04	---	$^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>3</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=4\text{A}$	---	15	20	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=3\text{A}$	---	21	30	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	6	---	S

**Dynamic and switching Characteristics**

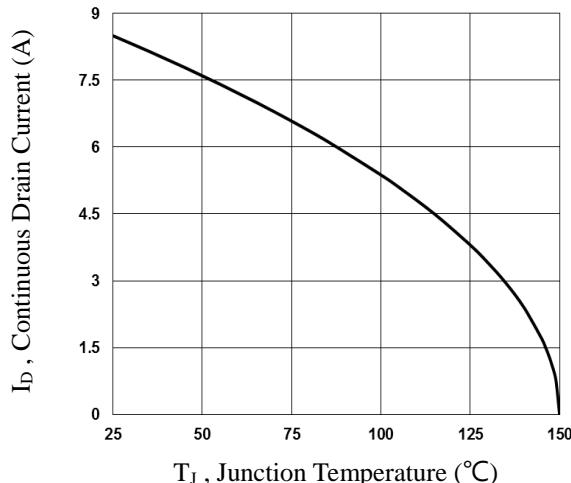
$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=4\text{A}$	---	5.2	10	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	0.6	1.2	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	2	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	2.8	5	ns
$T_r$	Rise Time <sup>2,3</sup>		---	7.2	14	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	15.8	30	
$T_f$	Fall Time <sup>2,3</sup>		---	4.6	9	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	370	740	pF
$C_{\text{oss}}$	Output Capacitance		---	70	140	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	50	100	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $f=1\text{MHz}$	---	2.2	4.5	$\Omega$

**Drain-Source Diode Characteristics and Maximum Ratings**

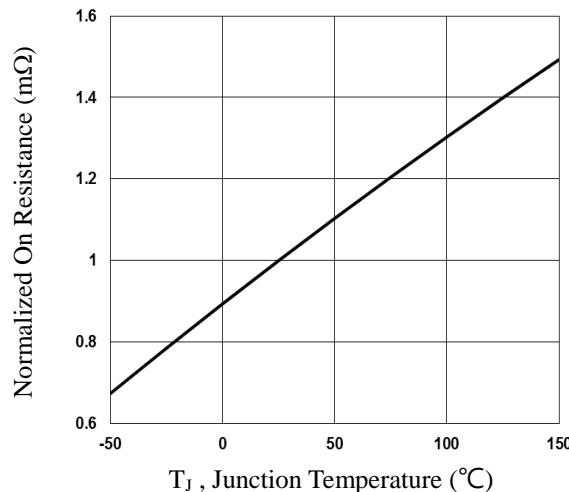
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	7.8	A
$I_{\text{SM}}$	Pulsed Source Current <sup>3</sup>		---	---	15.6	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>3</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

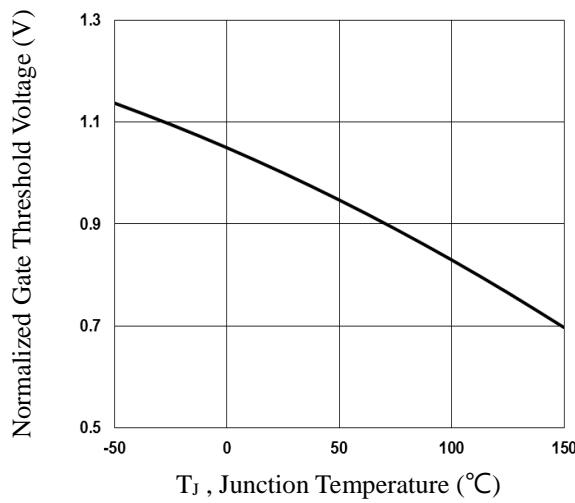
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.



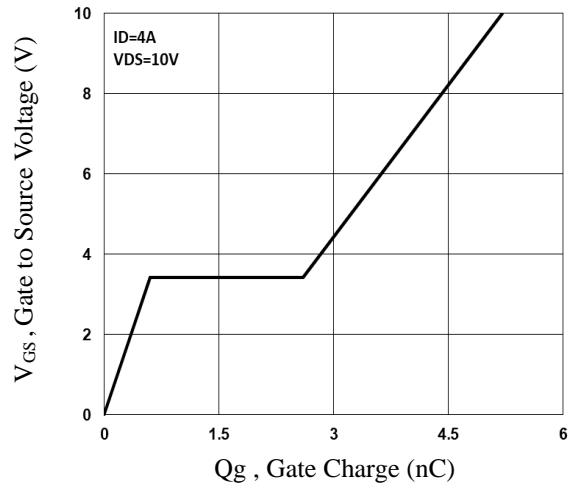
**Fig.1 Continuous Drain Current vs.  $T_J$**



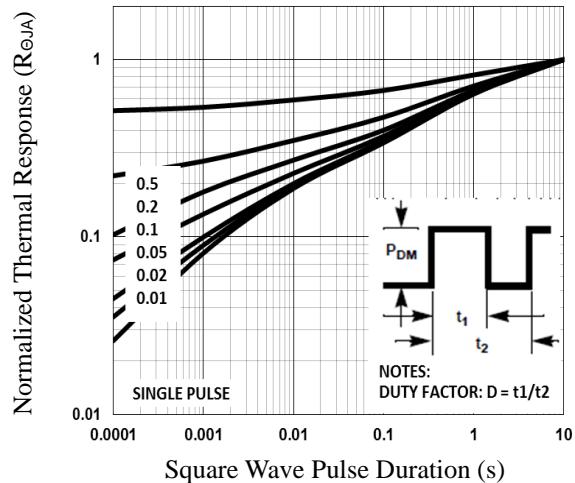
**Fig.2 Normalized RDS(ON) vs.  $T_J$**



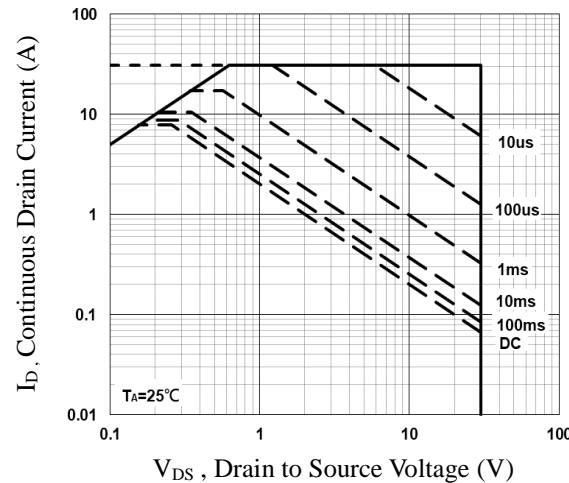
**Fig.3 Normalized  $V_{th}$  vs.  $T_J$**



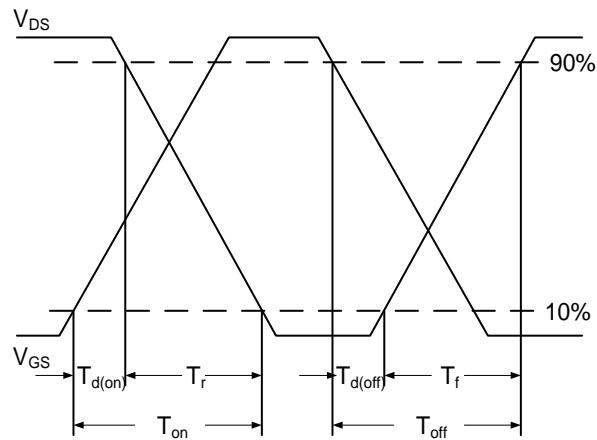
**Fig.4 Gate Charge Waveform**



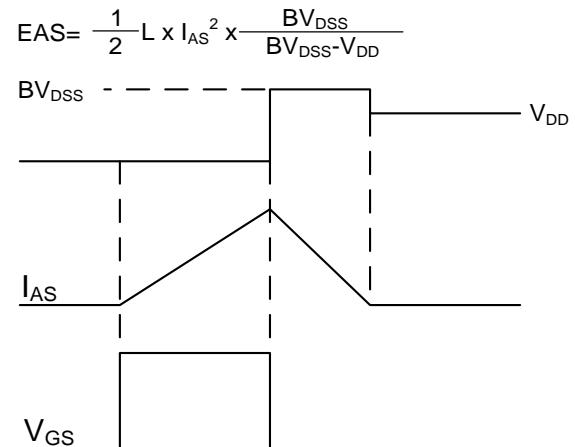
**Fig.5 Normalized Transient Response**



**Fig.6 Maximum Safe Operation Area**

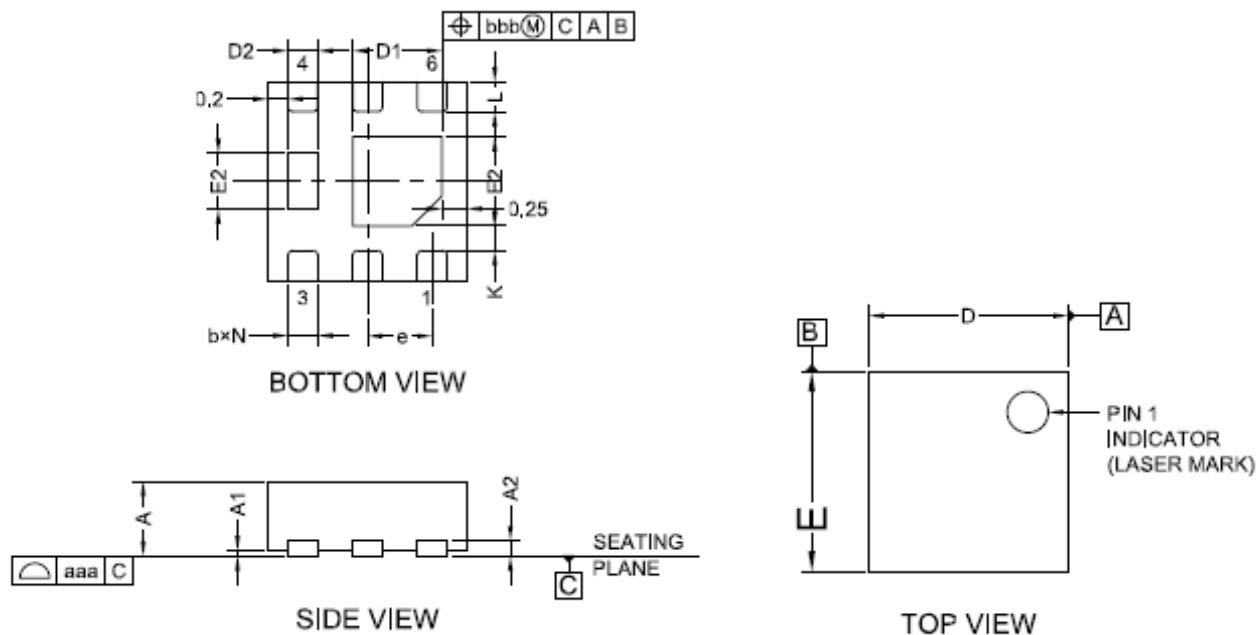


**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## DFN2X2-6L 2EP PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2	0.152REF		
b	0.25	0.30	0.35
D	1.95	2.00	2.05
D1	0.80	0.90	1.00
D2	0.25	0.30	0.35
E	1.95	2.00	2.05
E1	0.80	0.90	1.00
E2	0.46	0.56	0.66
e	0.65BSC		
L	0.25	0.30	0.35
J	0.40BSC		
K	0.20MIN		
N	6.00		
aaa	0.08		
bbb	0.10		

单击下面可查看定价，库存，交付和生命周期等信息

[>>SHIKUES\(时科\)](#)